

#### **AM124**

#### **Applications**

■ Tri Band Antenna Switch for GSM Handsets 5.4 x 4.0 x 1.7 mm

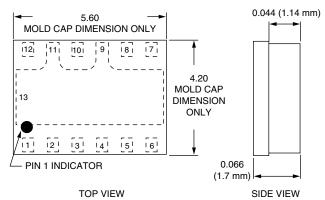
#### **Features**

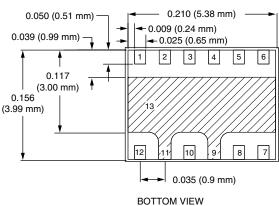
- Integrated Diplexer, T<sub>X</sub> LPFs, GaAs Switches and Decoder
- Low Current Drain, < 10 μA Typ.
- Low T<sub>X</sub> Insertion Loss (1.0 dB @ EGSM, 1.3 dB @ DCS/PCS)
- ESD Robust (>8 kV Contact, >15 kV Air)
- Capable of All Off Conditions for DCS/PCS Bands
- Combines GaAs PHEMT, CMOS and LTCC Process Technologies

#### **Description**

The AM124 is an EGSM/DCS/PCS antenna switch module with integrated SP2T/SP3T GaAs switches, decoder for 3 line control,  $T_X$  low pass filters and diplexer. It is housed in a 13 pin 5.4 x 4.0 x 1.7 mm LTCC multilayer ceramic package. The module has internal ESD protection to 2000 V. For protection to 8 kV and higher, contact factory for application note.

## **Outline Drawing**





Dimensions in inches (mm). Tolerance  $\pm$  0.2 mm unless otherwise specified.

# $T_X$ Specification

Mode	Parameter	Min.	Тур.	Max.	Unit
EGSM_T <sub>X</sub> to Ant	Passband	880	897.5	915	MHz
	Insertion Loss		1	1.2	dB
	Attenuation 1760–1830 MHz (2*F <sub>O</sub> )	30	35		dB
	Attenuation 2640–2745 MHz (3*F <sub>O</sub> )	30	35		dB
	Attenuation 3520–3660 MHz (4*F <sub>O</sub> )	30	40		dB
	Return Loss (I/O)	12	14		dB
	Isolation EGSM_T <sub>X</sub> - EGSM_R <sub>X</sub>	28	35		dB
	Isolation EGSM_T <sub>X</sub> - DCS_R <sub>X</sub>	30	40		dB
	Isolation EGSM_T <sub>X</sub> - PCS_R <sub>X</sub>	30	40		dB
	Harmonic Generation 1760–1830 MHz (2*F <sub>O</sub> )		80		dBc
	Harmonic Generation 2640–2745 MHz (3*F <sub>O</sub> )		80		dBc
	Input Power		34.5	35	dBm
	Current Consumption		10	100	μΑ
DCS/PCS_T <sub>X</sub> to Ant	Passband - DCS_T <sub>X</sub>	1710	1747.5	1785	MHz
	Passband - PCS_T <sub>X</sub>	1850	1880	1910	MHz
	Insertion Loss - DCS_T <sub>X</sub>		1.5	1.7	dB
	Insertion Loss - PCS_T <sub>X</sub>		1.3	1.5	dB
	Attenuation 3420–3820 MHz (2*F <sub>O</sub> )	25	35		dB
	Attenuation 5130–5730 MHz (3*F <sub>O</sub> )	30	40		dB
	Return Loss DCS_T <sub>X</sub> (I/O)	12	15		dB
	Return Loss PCS_T <sub>X</sub> (I/O)	14	18		dB
	Isolation DCS/PCS_T <sub>X</sub> - EGSM_R <sub>X</sub>	25	30		dB
	Isolation DCS/PCS_T <sub>X</sub> - DCS_R <sub>X</sub>	23	28		dB
	Isolation DCS/PCS_T <sub>X</sub> - PCS_R <sub>X</sub>	25	30		dB
	Harmonic Generation 3420–3820 MHz (2*F <sub>O</sub> )		70		dBc
	Harmonic Generation 5130–5730 MHz (3*F <sub>O</sub> )		75		dBc
	Input Power		32.5	33	dBm
	Current Consumption		10	100	μΑ

## $\mathbf{R}_{\mathbf{X}}$ Specification

Mode	Parameter	Min.	Тур.	Max.	Unit
Ant to EGSM_R <sub>X</sub>	Passband	925	942.5	960	MHz
	Insertion Loss		0.9	1.1	dB
	Return Loss (I/O)	14	18		dB
	Isolation EGSM_T <sub>X</sub> - Ant	17	21		dB
	Input Power		10		dBm
	Current Consumption		5	15	μА
Ant to DCS_R <sub>X</sub>	Passband	1805	1842.5	1880	MHz
	Insertion Loss		1.2	1.4	dB
	Return Loss (I/O)	14	17		dB
	Isolation DCS_T <sub>X</sub> - Ant	15	18		dB
	Isolation PCS_R <sub>X</sub> - Ant	23	26		
	Input Power		10		dBm
	Current Consumption		5	15	μА
Ant to PCS_R <sub>X</sub>	Passband	1930	1960	1990	MHz
	Insertion Loss		1.2	1.4	dB
	Return Loss (I/O)	12	15		dB
	Isolation PCS_T <sub>X</sub> - Ant	14	17		dB
	Isolation DCS_R <sub>X</sub> - Ant	23	26		
	Input Power		10		dBm
	Current Consumption		5	15	μΑ
Control Voltage	V <sub>C1</sub> , V <sub>C2</sub> , V <sub>C3</sub> High "1"	V <sub>CC</sub> -0.6		V <sub>CC</sub>	V
	V <sub>C1</sub> , V <sub>C2</sub> , V <sub>C3</sub> Low "0"	0		0.5	V
Supply Voltage	V <sub>CC</sub>	2.6	3.0	5.0	V

## **Absolute Maximum Ratings**

Characteristic	Value	
Operating Temp Range (T <sub>OP</sub> )	-30 to +85°C	
Storage Temp Range (T <sub>STG</sub> )	-40 to +85°C	
Input Power, EGSM_T <sub>X</sub> (P <sub>IN</sub> EGSM_T <sub>X</sub> )	36 dBm	
Input Power, DCS_T <sub>X</sub> (P <sub>IN</sub> DCS_T <sub>X</sub> )	34 dBm	
Control Voltage Logic 0 (V <sub>C1</sub> , V <sub>C2</sub> , V <sub>C3</sub> )	-0.1 to +0.8 V	
Control Voltage Logic 1 (V <sub>C1</sub> , V <sub>C2</sub> , V <sub>C3</sub> )	V <sub>CC</sub> + 0.1 V	
Supply Voltage (V <sub>CC</sub> )	6 V	
Nominal I/O Impedances (T <sub>X</sub> , R <sub>X</sub> , Ant)	50 Ω	

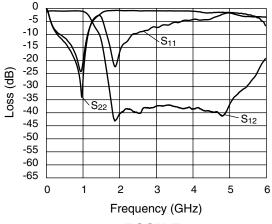
#### **Truth Table**

Switch Mode	V <sub>C1</sub>	V <sub>C2</sub>	V <sub>C3</sub>
EGSM_R <sub>X</sub> , DCS_R <sub>X</sub>	0	0	0
PCS_R <sub>X</sub> , EGSM_R <sub>X</sub>	0	0	1
EGSM_T <sub>X</sub> , DCS_R <sub>X</sub>	1	0	0
DCS/PCS_T <sub>X</sub> , EGSM_R <sub>X</sub>	0	1	0
EGSM_T <sub>X</sub> , DCS/PCS_Off <sup>1, 2</sup>	1	1	1

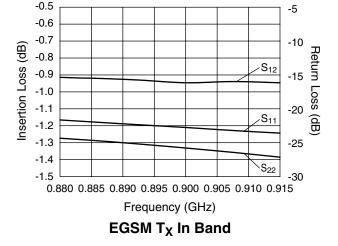
<sup>1.</sup> DCS/PCS\_T<sub>X</sub>, DCS\_R<sub>X</sub> and PCS\_R<sub>X</sub> paths can be turned off simultaneously. Apply a V<sub>CC</sub> voltage to the DCS/PCS\_T<sub>X</sub> path. Set control voltages as shown in the truth table. Chosen path is EGSM\_T<sub>X</sub>. All other paths are in the off condition.

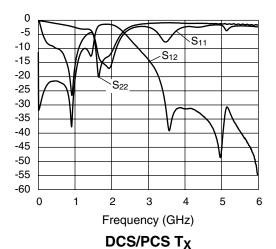
2. V<sub>CC</sub> voltage must be applied 10 ns (min.) before application of control voltages (V<sub>C1</sub>, V<sub>C2</sub>).

## Typical Performance Data (0, +3 V)



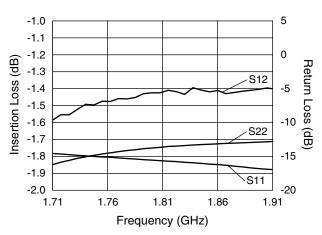
EGSM TX



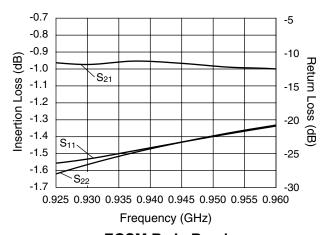


-5 S<sub>11</sub> -10 Loss (dB) -15 -20 S<sub>21</sub> -25 -30

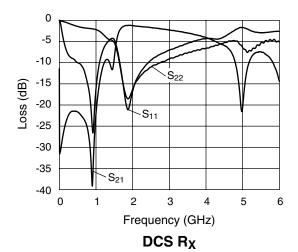
0 S<sub>22</sub> -35 6 Frequency (GHz) EGSM RX

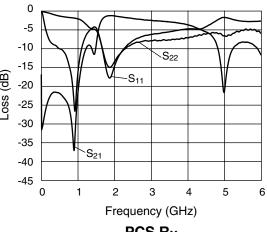


DCS/PCS TX In Band



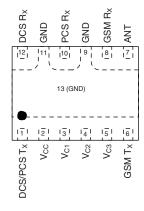
EGSM RX In Band

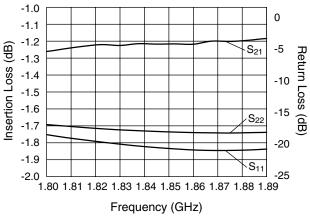


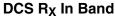


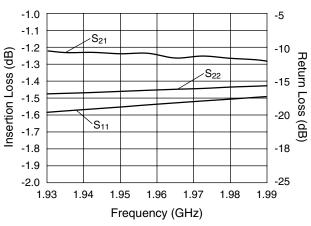
# PCS R<sub>X</sub>

## Pin Out (Top View)







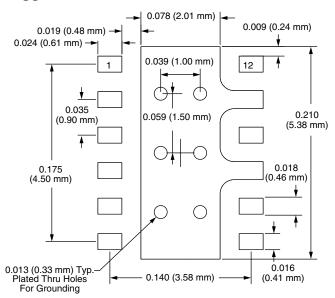


PCS R<sub>X</sub> In Band

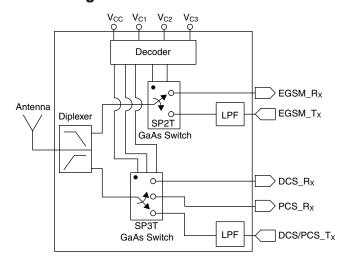
# **Pin Out Description**

Pin Number	Description	Remarks
1	DCS/PCS_T <sub>X</sub>	50 $\Omega$ Terminating Impedance
2	V <sub>CC</sub>	Power Supply
3	V <sub>C1</sub>	Control Voltage Input
4	V <sub>C2</sub>	Control Voltage Input
5	V <sub>C3</sub>	Control Voltage Input
6	GSM_T <sub>X</sub>	50 $\Omega$ Terminating Impedance
7	ANT	50 $\Omega$ Terminating Impedance
8	GSM_R <sub>X</sub>	50 $\Omega$ Terminating Impedance
9, 11, 13	GND	Ground
10	PCS_R <sub>X</sub>	50 $\Omega$ Terminating Impedance
12	DCS_R <sub>X</sub>	50 $\Omega$ Terminating Impedance

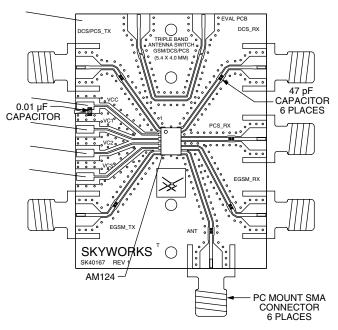
## **Suggested Land Pattern**



### **Block Diagram**



#### **Evaluation PCB**



Material: FR4

The circuit board used in the final application should employ RF circuit design techniques. RF signal lines should have 50  $\Omega$  impedance. The package bottom ground plane should be connected directly to PCB ground plane. A sufficient number of via holes should be used to connect the top and bottom ground planes. The evaluation circuit board shown is available upon request.